



Customer Information Notification

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QUALITY

Management Summary

NXP Semiconductors announces the Reference Manual update for MKE06/MKE04(Z64,Z128), and Datasheet update for MKE02/MKE04/MKE06.

Change Category

- | | | | | |
|----------------------------------------------|----------------------------------------------------------------------------|----------------------------------------------------|-----------------------------------------|--------------------------------------------------------------------|
| <input type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test Location | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Process | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input checked="" type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware | <input checked="" type="checkbox"/> Other - reference manual and datasheet | | | |

MKE02/MKE04/MKE06 Datasheet Update and MKE06,MKE04(Z64,Z128)Reference Manual Update

Description

NXP Semiconductors announces that the MKE04Z8 DS has been updated to Rev 4(MKE04P24M48SF0_Rev.4).

NXP Semiconductors announces that the MKE02 DS has been updated to Rev 5(MKE02P64M40SF0_Rev.5) and Rev 6(MKE02P64M20SF0_Rev.6).

NXP Semiconductors announces that the MKE06,MKE04(Z64,Z128) DS has been updated to Rev 5 (MKE04P80M48SF0_Rev.5, MKE06P80M48SF0_Rev.5).

NXP Semiconductors announces that the MKE06,MKE04(Z64,Z128) Reference Manual has been updated to Rev 4 (MKE04P80M48SF0RM_Rev.4,MKE06P80M48SF0RM_Rev.4).

The revision history included in the updated document provides a detailed description of the changes.

Changes are summarized below:

MKE04P24M48SF0_Rev.4:

1. Added a new section of Thermal operating requirements.
2. Added a footnote of "Max power supply ramp rate is 500 V/ms." to Operating voltage in the DC characteristics.
3. Added a footnote to the 'factory trimmed internal oscillator accuracy' in the External oscillator (OSC) and ICS characteristics.

MKE02P64M40SF0_Rev.5:

1. Added a footnote of "Max power supply ramp rate is 500 V/ms." to Operating voltage in the DC characteristics.
2. Added a footnote to the 'factory trimmed internal oscillator accuracy' in the External oscillator (OSC) and ICS characteristics

MKE02P64M20SF0_Rev.6:

1. Added a footnote of "Max power supply ramp rate is 500 V/ms." to Operating voltage in the DC characteristics.
2. Added a footnote to the 'factory trimmed internal oscillator accuracy' in the External oscillator (OSC) and ICS characteristics

MKE06P80M48SF0_Rev.5/MKE04P80M48SF0_Rev.5:

1. Added a footnote of "Max power supply ramp rate is 500 V/ms." to Operating voltage in the DC characteristics.
2. Added a footnote to the 'factory trimmed internal oscillator accuracy' in the External oscillator (OSC) and ICS characteristics.

MKE04P80M48SF0RM_Rev.4/MKE06P80M48SF0RM_Rev.4:

- A.17 WDOG changes: Updated the access of CNTH and CNTL registers to be R/W in the memory map.
- A.19 FTMRE changes: Updated the access of FPROT and FOPT to be RW. Updated the figures of 128/64 KB flash protection memory map.
- A.21 ICS changes: Updated the access of ICS_S to be RW in the ICS memory map.
- A.31 SPI changes: Updated the S register to be RW and S[SPMF] to be W1C, added a note to the S[SPMF].
- A.33 MSCAN changes: Updated the access of the receive registers and TTSRH, TTSRL to be Read only and added note to the receive registers.

The updated Datasheet can be found at:

<https://www.nxp.com/search?category=documents&keyword=MKE02&filter=type>>Data Sheet&siblings=false>

The updated Reference manual can be found at:

<https://www.nxp.com/search?category=documents&keyword=MKE&filter=type>>Reference Manual&siblings=false>

Reason

The Datasheets and the Reference Manual have been updated to provide additional technical clarification on some device features.

Identification of Affected Products

Product identification does not change

No impact on form, fit, function, reliability or quality.

Data Sheet Revision

A new datasheet will be issued

Additional information

Additional documents: [view online](#)

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

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Name Jonson Chen

Position Application Engineer

e-mail address <mailto:Jonson.chen@nxp.com?subject=Support>

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NXP Quality Management Team.

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NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

NXP Semiconductors
High Tech Campus, 5656 AG Eindhoven, The Netherlands

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